

CLAIMS

1. A hexagonal heatsink system, comprising:

an electronic circuit board that comprises a plurality of processors; and

a plurality of heatsink components, wherein

5 the plurality of heatsink components comprises:

a base plate; and

a plurality of first fins that extends from the base plate,

the plurality of heatsink components is attached to the electronic circuit board via the plurality of first fins,

10 the plurality of heatsink components is configured to transfer heat generated from the electronic circuit board, and

a shape of the base plate is a hexagonal shape.

2. The hexagonal heatsink system of claim 1, wherein the plurality of heatsink

15 components further includes a plurality of second fins the extends from the base plate.

3. The hexagonal heatsink system of claim 2, wherein

the plurality of first fins extends along a first direction, and

the plurality of second fins extends along a second direction different from the

20 first direction.

4. The hexagonal heatsink system of claim 3, wherein the first direction is perpendicular to the second direction.

5. The hexagonal heatsink system of claim 2, wherein the plurality of heatsink components further includes a cooling device between a first fin of the plurality of second fins and a second fin of the plurality of second fins.

5 6. The hexagonal heatsink system of claim 1, wherein each fin of the plurality of first fins includes a slot to attach the plurality of heatsink components to the electronic circuit board.

7. The hexagonal heatsink system of claim 1, wherein
10 the base plate has six vertices, and
the plurality of first fins extends from the six vertices of the base plate.

8. The hexagonal heatsink system of claim 1, wherein
the base plate has six vertices,
15 the plurality of first fins includes three fins, and
the three fins extend from one of odd vertices of the six vertices or even vertices of the six vertices.